



FMIAA001xxx*DXANFGO

Thin Film Chip Attenuators

* xxx specifies attenuation e.g. 050 is 5.0 dB.

FEATURES

- Surface mount chip attenuator ideal for applications (hybrid circuits) requiring precision attenuation in a small form factor
- Single component reduces circuit area and board space while replacing discrete components and improving performance
- Thin film technology ensures a stable attenuator over time and temperature
- High reliability
- Wire bondable pads on top surface
- Ground wrap eliminates need for wire for shunt element
- Solder or conductive epoxy attach
- Excellent high-frequency response — DC through 22 GHz
- 50 Ohm impedance
- Power rating 250 mW
- Substrate 99.9% alumina with TaN/TiW/Ni/Au
- Attenuation range of -1 dB to -20 dB in 1-dB steps (0.5 dB or custom attenuations available)
- Latched Soft Start to limit power consumption

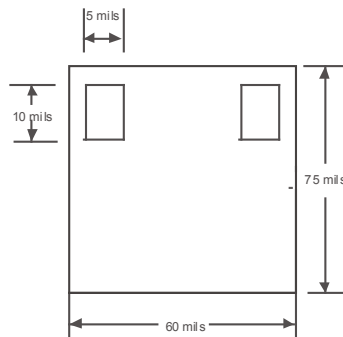
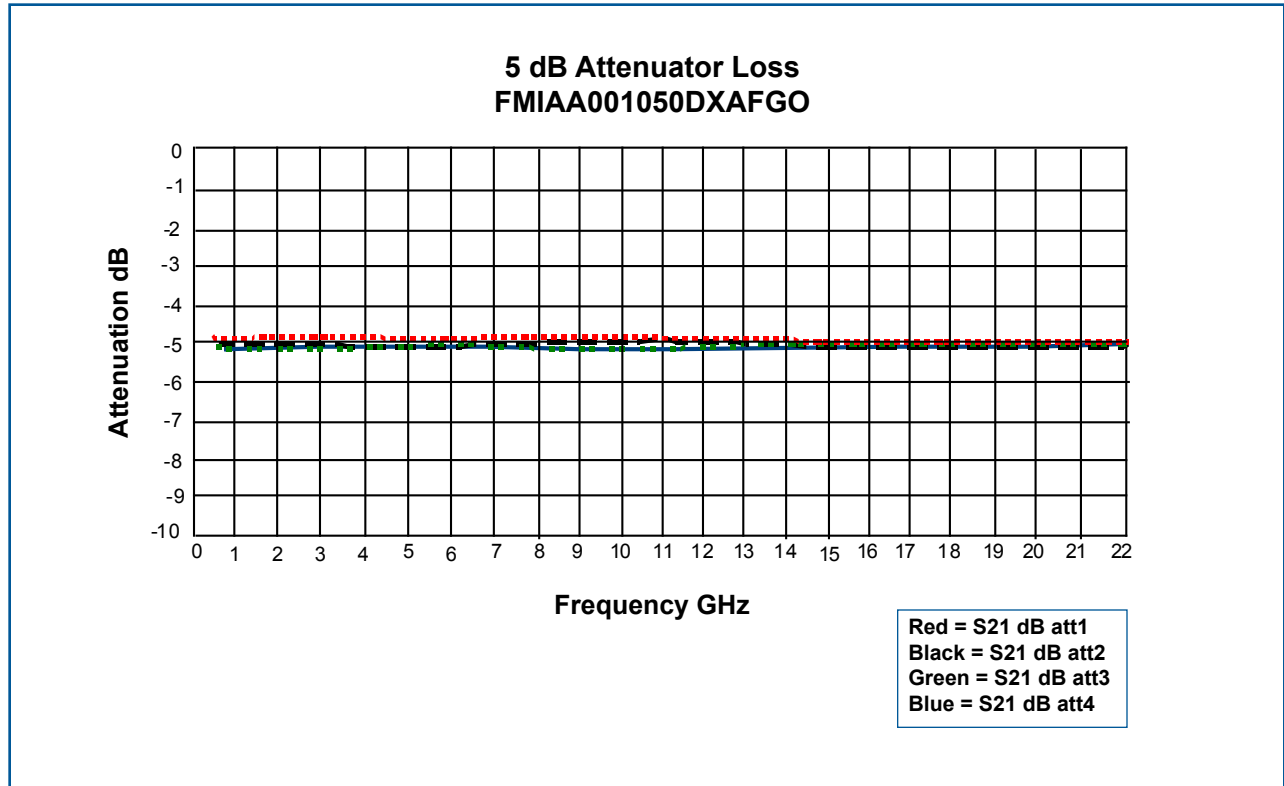
ELECTRICAL DATA

Parameter	Specification
Frequency	DC to 22 GHz
Attenuation	1 to 20 dB in 1-dB increments
Attenuation Accuracy	±0.5 dB
Return Loss	1.45:1 VSWR; -15 dB, DC to 15 GHz 1.90:1 VSWR; -10 dB, 15 to 22 GHz
Impedance	50 Ohms
Power Rating	250 mW, solder attach to heat sink
Size	60 X 75 X 10 mil
Substrate Material	99.9% Alumina
Resistor Material	Tantalum Nitride
Bond Pads	Wire Bondable Gold
Backside Metal	Solderable or Epoxy attach Ni/Au

Spectrum Microwave

Tel: 508-485-6350 Fax: 508-485-5168
165 Cedar Hill Street, Marlborough, MA 01752
www.SpectrumMicrowave.com

5 dB Thin Film Chip Attenuator Measured Performance Data



Mechanical Outline